

ABSTRACT

A spindle for a wafer carrying manipulator is disclosed. The spindle includes: a plurality of driving shafts being arranged coaxially; a plurality of driving motors for driving the driving shafts to rotate around a housing relatively; a plurality of bearings having inner
5 and outer sides abutting against the driving shafts and the housing respectively; and a plurality of circular gratings for recording rotation angle data of the driving shafts. At least one driving shaft is formed by a first shaft body, a second shaft body, and a third shaft body; the second shaft body has a step structure, and an end portion of the first shaft body and an end of the step structure form a first chamber for mounting one circular grating; an end
10 portion of the third shaft body and the other end of the step structure form a second chamber for mounting one bearing.

[FIG. 1]